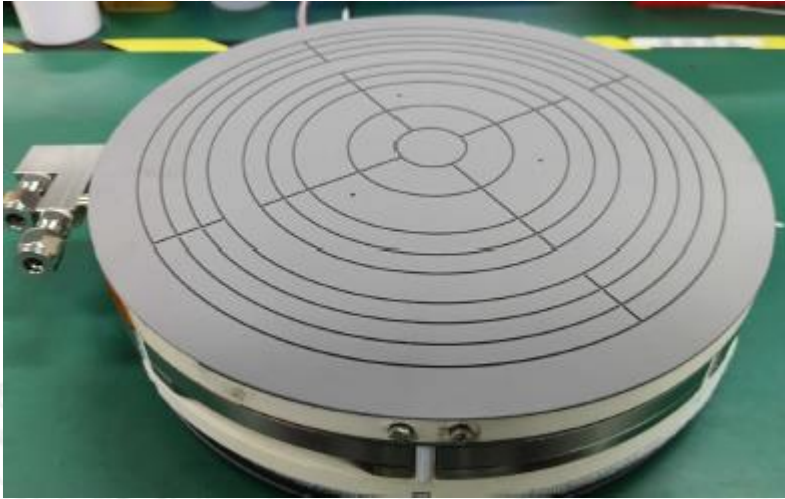
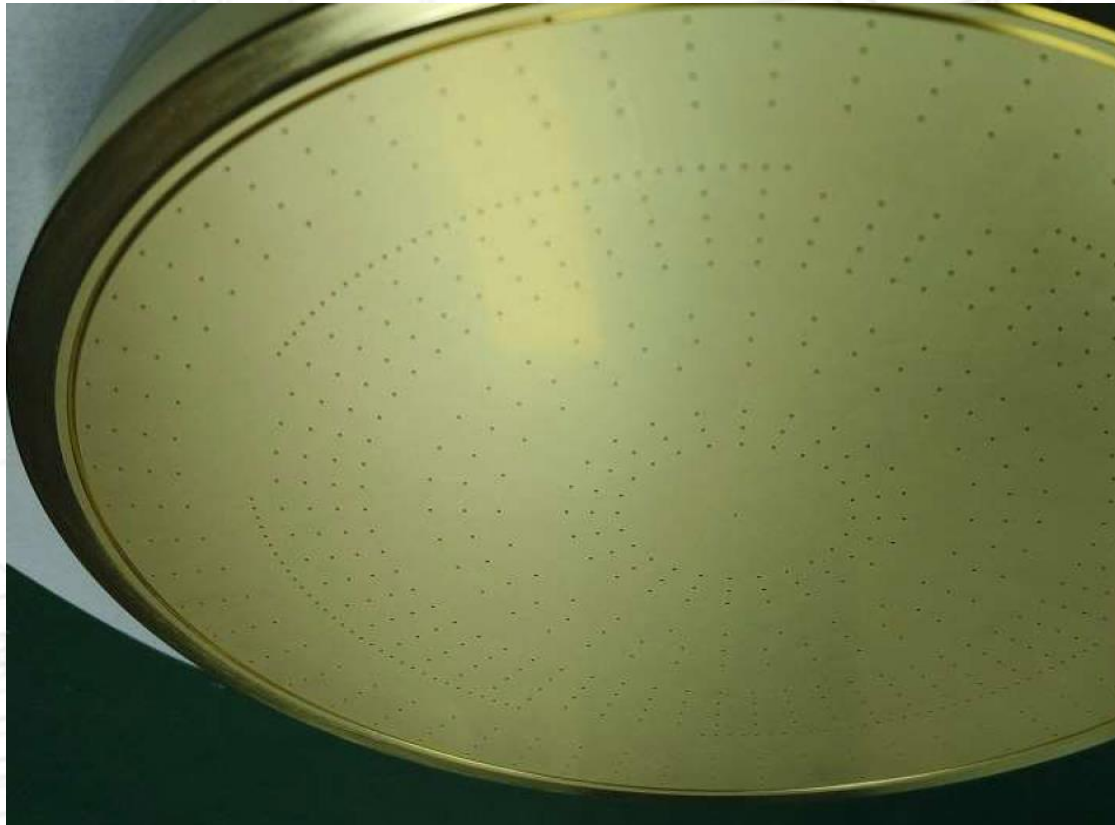


WAFER CHUCK---WAT



No.	Item	Specifications
		C1
1	Size (mm)	310/205 (±0.15)
2	Thickless	48.5~49.0
3	Taiko Diameter (mm)	/
4	Taiko Height (mm)	/
5	Flatness - Ambient temperature (mm)	≤0.01
6	Flatness - High temperature (mm)	≤0.015
7	Parallelism (mm)	≤0.01
8	Temperature Operating Range (°C)	0~150
9	High-Temperature Uniformity (°C)	≤1.5°C
10	Service Lifespan (H)	≥3000 hr
11	Static Single-Point Surface Impedance Measurement (MΩ)	≤1
12	Voltage Endurance (V)	/
13	Current Endurance (A)	/
14	Leakage Current	Comprehensive Testing for PA Grade
15	Vacuum Suction Negative Pressure/Non-Sucking Wafer (KPa)	≥-15
16	Negative Pressure Wafer Suction (KPa)	≤-80
Note	This parameter is for this product model, and different parameters for wafer chuck can be provided based on testing requirements.	

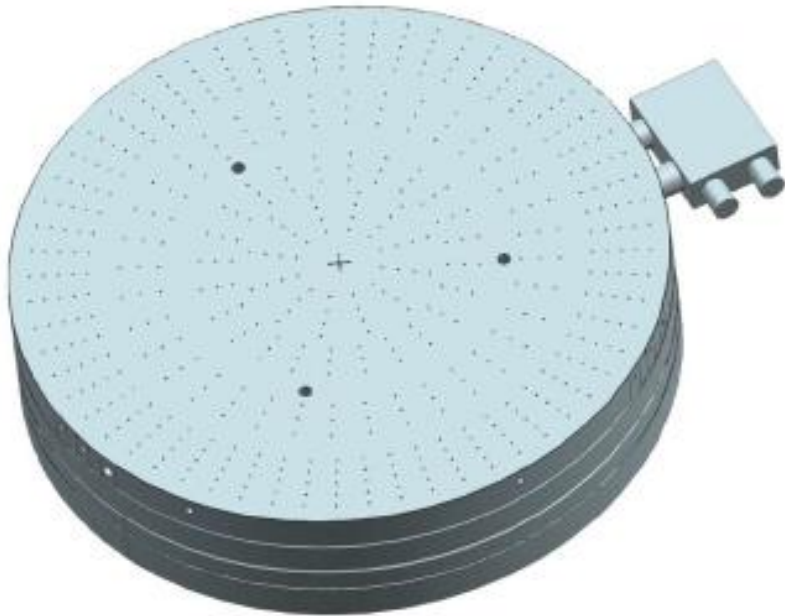
WAFER CHUCK---IGBT



No.	Item	Specifications
		B2
1	Size (mm)	310/205 (± 0.15)
2	Thickless	45.0~45.10
3	Taiko Diameter (mm)	/
4	Taiko Height (mm)	/
5	Flatness - Ambient temperature (mm)	≤ 0.01
6	Flatness - High temperature (mm)	≤ 0.015
7	Parallelism (mm)	≤ 0.01
8	Temperature Operating Range ($^{\circ}\text{C}$)	0~150
9	High-Temperature Uniformity ($^{\circ}\text{C}$)	$\leq 1.5^{\circ}\text{C}$
10	Service Lifespan (H)	≥ 3000 hr
11	Static Single-Point Surface Impedance Measurement ($\text{M}\Omega$)	≤ 1
12	Voltage Endurance (V)	3000
13	Current Endurance (A)	200
14	Leakage Current	/
15	Vacuum Suction Negative Pressure/Non-Sucking Wafer (KPa)	≥ -15
16	Negative Pressure Wafer Suction (KPa)	≤ -80
Note	This parameter is for this product model, and different parameters for wafer chuck can be provided based on testing requirements.	

WAFER CHUCK

Temperature Variation between High and Low Temperatures

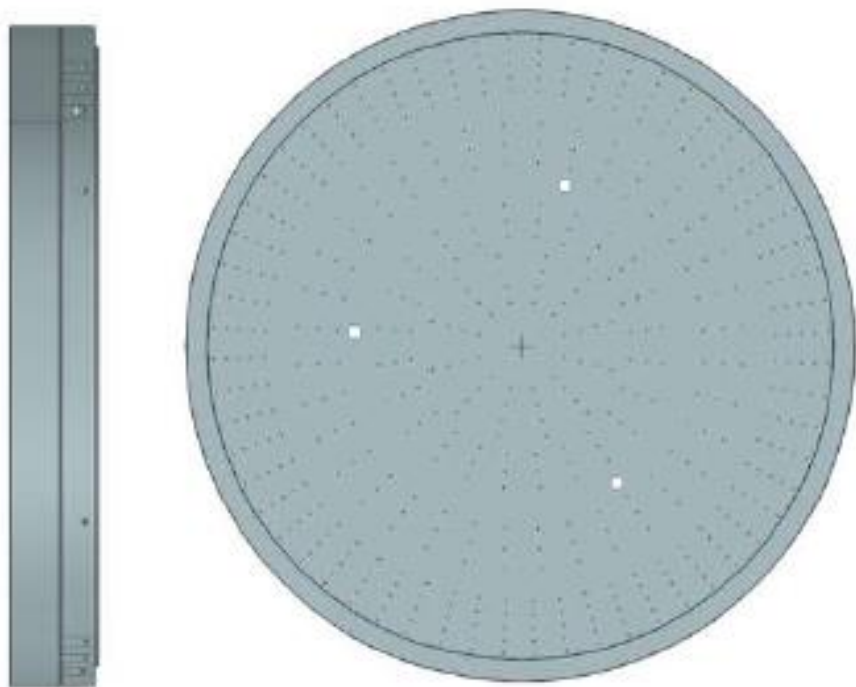


No.	Item	Parameter
1	Size (mm)	305/205 (±0.15)
2	Thickness	45.0~45.10
3	Taiko Diameter (mm)	191.8±0.1
4	Taiko Height (mm)	1.0~1.10
5	Flatness - Ambient temperature (mm)	≤0.01
6	Flatness - High temperature (mm)	≤0.015
7	Parallelism (mm)	≤0.01
8	Heating Wire Material	Ceramic Mica Heating
9	Heating Power	By Combining Heating Units 600W
10	Rated Operating Voltage	220V/50Hz / 110V/50Hz
11	Temperature Range for Heating	0°C~250°C
12	Operating Environment Temperature	-50°C~200°C
13	High-Temperature Uniformity	≤1.5°C
14	Rate of Temperature Increase	5°C/min
15	Temperature Sensing Specifications	PT100
16	Temperature Sensing Accuracy	±0.1°C
17	Low-Temperature Uniformity	≤1.0°C
18	Service Lifespan	≥3000 hr
19	Static Single-Point Surface Impedance Measurement	≤1MΩ

WAFER CHUCK

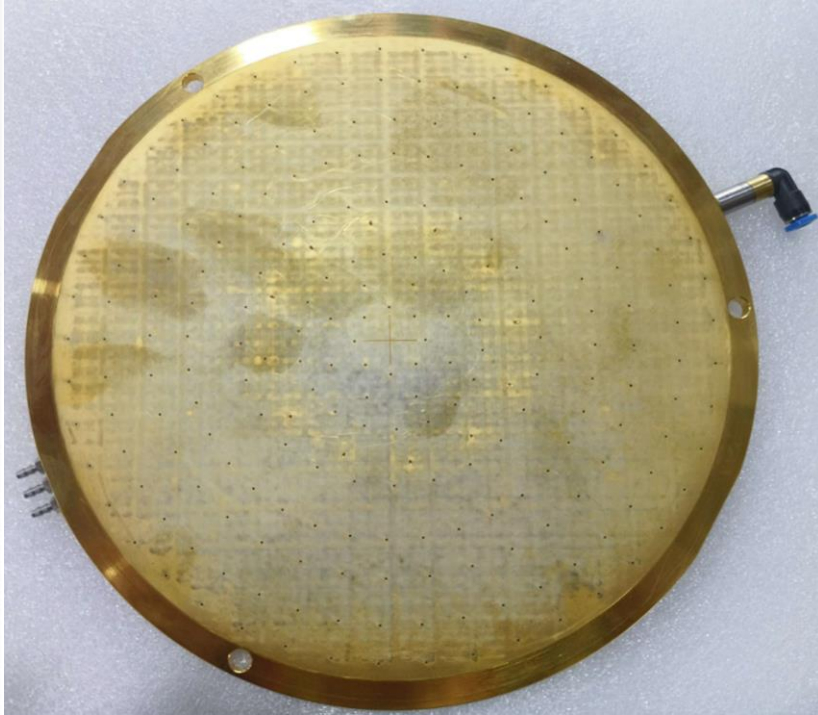


Temperature Variation in High Temperature



No	Item	Parameter
1	Size (mm)	305/205 (± 0.15)
2	Thickless	28.0~28.10
3	Taiko Diameter (mm)	191.8 \pm 0.1
4	Taiko Height (mm)	1.0~1.10
5	Flatness - Ambient temperature (mm)	≤ 0.01
6	Flatness - High temperature (mm)	≤ 0.015
7	Parallelism (mm)	≤ 0.01
8	Temperature Range for Heating ($^{\circ}\text{C}$)	0~150
9	High-Temperature Uniformity ($^{\circ}\text{C}$)	$\leq 1.5^{\circ}\text{C}$
10	Service Lifespan (H)	≥ 3000 小时
11	Static Single-Point Surface Impedance Measurement ($\text{M}\Omega$)	≤ 1

WAFER CHUCK---REFURBISHMENT




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扫一扫上面的二维码图案，加我为朋友

Thanks